CLAIMS

1. A polishing composition for polishing copper or a copper alloy and a resin, comprising:

alumina abrasive grains;

glycine;

an anionic surfactant; and

water, wherein

the content of the alumina abrasive grains is 3.0 mass % or less, and

the content of the anionic surfactant is 0.5 mass % or more.

2. The polishing composition according to claim 1, wherein the content of the glycine is 0.3 mass % or more.

3. The polishing composition according to claim 1 or 2, wherein the anionic surfactant is an alkylbenzenesulfonic acid.

4. The polishing composition according to any one of claims 1 to 3, having a pH of 7.0 or more and 11.0 or less.